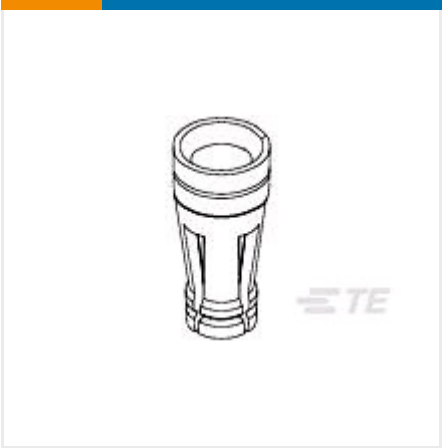




+ CONNECTORS
DISCRETE SOCKETS



✓ Active

TE CONNECTIVITY (TE)
8134-HC-8P3=TIN/LEAD PER 3.3.2
[HOLTITE](#) | [HOLTITE](#)

8134-HC-8P3
TE Internal Number: 7-1437514-1

[Not EU RoHS Compliant](#)
[Not EU ELV Compliant](#)

Hole Size (Recommended) 1.47 mm [.058 in]
Socket Length 3.45 mm [.136 in]
Sealant Without
Mating Pin Diameter Range .64 – .89 mm [.025 – .035 in]
Termination Method to PC Board Through Hole - Press-Fit

[↓](#) **PRODUCT DRAWING**
English

[↓](#) **3D PDF**

DOCUMENTATION

Product Drawings

HOLTITE CONTACTS
PDF
English

CAD Files

Customer View Model
3D_IGS.ZIP
English

Customer View Model
3D_STP.ZIP
English

Customer View Model

2D_DXF.ZIP

English

3D PDF

PDF

English

Product Specifications

Application Specification

AUGAT HOLTITE Sockets

PDF

English

Product Specification

AUGAT HOLTITE Sockets

PDF

English

FEATURES



Please review product documents or [contact us](#) for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

Connector & Contact Terminates To Printed Circuit Board

Product Type Contact

Profile Zero

Wire/Cable Type Discrete Wire

Body Features

Sealant Without

Sleeve Plating Material Tin

Sleeve Material Copper

Contact Features

Contact Current Rating (Max) (A) 5

Contact Type Socket

Contact Spring Plating Material Tin

Contact Transmits (Typical) Signal (Data)/Power

Contact Base Material Beryllium Copper

Contact Mating Area Plating Material Tin-Lead

Socket Type Discrete

Termination Features

Termination Method to PC Board Through Hole - Press-Fit

Termination Method to Wire/Cable Solder

Insertion Method Hand/Semi-Automatic

Dimensions

Socket Length 3.45 mm [.136 in]
Hole Size (Recommended) 1.47 mm [.058 in]
Mating Pin Diameter Range .64 – .89 mm [.025 – .035 in]
PCB Thickness (Recommended) .79 – 3.18 mm [.03 – .05 in]

Usage Conditions

Operating Temperature Range -65 – 125 °C [-85 – 257 °F]

Packaging Features

Packaging Method Loose Piece
Packaging Quantity 2500

Other

Spring Material Beryllium Copper

PRODUCT COMPLIANCE



Statement of Compliance

Statement of Compliance
PDF